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(54) Title: ELECTROSTATIC CHUCK WITH HIGH-DENSITY PLASMA BARRIER COATING

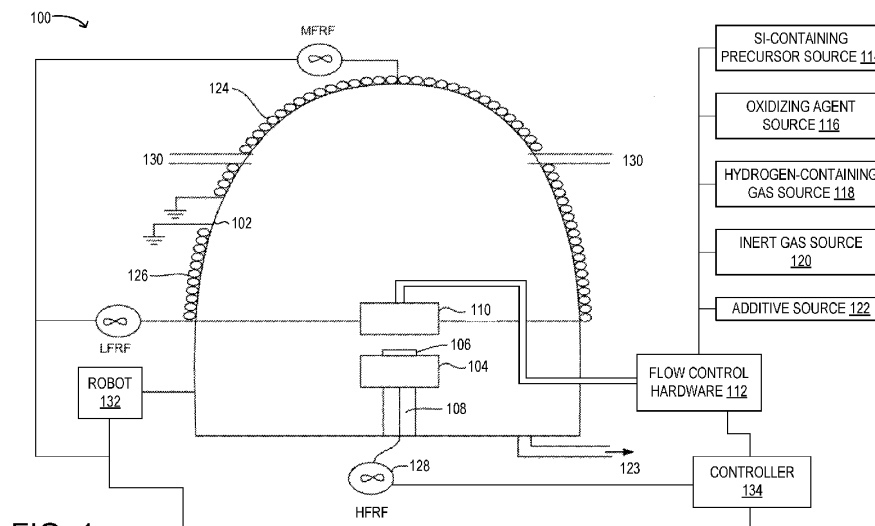


FIG. 1

(57) Abstract: An electrostatic chuck comprises a substrate-facing surface comprising one or more substrate contact areas. The electrostatic chuck further comprises a high-density plasma (HDP) barrier coating on at least a portion of the one or more substrate contact areas.

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